

PCN20250828000.1
Qualification of additional Assembly sites for select QFN devices
Change Notification / Sample Request

Date: August 28, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250828000.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC2340R53N0RKPR	NULL
CC2340R52N0RGER	NULL
CC2340R52N0RKPR	NULL
CC2340R22E0RKPR	NULL
CC2340R21N0RGER	NULL
CC2340R22N0RKPR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20250828000.1	PCN Date:	August 28, 2025
Title:	Qualification of additional Assembly sites for select QFN devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	November 26, 2025	Sample requests accepted until:	October 27, 2025*

***Sample requests received after October 27, 2025 will not be supported.**

Change Type:

<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

QFN Build Sites	
Assembly Sites	CLARK, MLA, CARZ, ASEN, TIEMA, UTL1/UTL3, CDAT
Mount Compound	4207123
	4211470
	SID#1400410104
	SID#1400020112
	SID#PZ0031
	SID#435143
	SID#443156
	SID#PZ0035
Mold Compound	4222198
	SID#1801512111
	4208625
Leadframe Finish	NiPdAu, Matte Sn
Bond Wire (mil)	CU (0.8 mil)
** Topside Marking (ECAT value)	Remove G4

** - Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

No Change

REACH

No Change

Green Status

No Change

IEC 62474

No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CLARK	QAB	PHL	Angeles City, Pampanga
MLA	MLA	MYS	Kuala Lumpur
CARZ	CSZ	CHN	Suzhou
ASEN	ASN	CHN	Nantong
TIEMA	CU6	MYS	Melaka
UTL1	NSE	THA	Bangkok
UTL3	UT3	THA	Bangpakong
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



Product Affected:

CC2340R21N0RGER	CC2340R52N0RGER	FRE016RKPR	
CC2340R22E0RKPR	CC2340R52N0RKPR		
CC2340R22N0RKPR	CC2340R53N0RKPR		

QFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CDAT TLV75733PDRV	CDAT TPS65992DADRJK	CDAT TLC6983RRF
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	2/44/0	3/66/0 (ADS5296RGC)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	Clark-AT LP5912Q1.2DRVQRQ1	Clark-AT ONET4291VARGP	Clark-AT SH6966ACC0RGC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	1/22/0	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	ASEN CSD87502Q2	ASEN TPS65988CFRSH	ASEN TPS65126RSH
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	1/77/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0 (TIOL1XXDMW)	3/231/0	2/122/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (CSD58911Q2)	3/66/0	1/22/0 (TPS65987DDJRSRSH)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	CARZ TLV75733PDRV	CARZ TPD5S330RJK	CARZ UCD9211RHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0 (ADS8548SRGC)
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (DS90LV028AQDQF)	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	UTL1 TPS717XXQDRVQ1	UTL1 LM73606QRNPQ1	UTL1 SH6966ADU0RGC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	2/154/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	2/154/0	3/231/0
UHAST /AC	Unbiased HAST,130C/85%RH Or Autoclave 121C	96 hours	3/231/0	2/154/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	2/44/0	1/22/0	1/22/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	UTL3 TCAN1042DRBQ1 TPS61025DRC TCAN1051VDRBQ1	UTL3 TPS22990DML TPS62261DRV TPS62080ADSG	UTL3 CC2541F256RHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/230/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	1/22/0	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	Pass	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	TIEMA LM26LVQISDJ1NC	TIEMA LP8548B1ASQX04	TIEMA DS125BR401Q4DK LP3971SQ-D510/NOPB
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM25066APSMGH N)	3/66/0 (LMK00334RTVTQ1)	1/22/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	TIM (MLA) PCOBTF100RLQ	TIM (MLA) CDCM1804RGE	TIM (MLA) MSP430FR5739IRHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0 (TPS62170DSG)	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/135/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS62170DSG)	3/66/0 (TSC2200RHB)	3/66/0 (SN75DP128ARTQ)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

TLV75733PDRV, LP8548B1ASQX04, LM26LVQISDJ1NC, CSD87502Q2, PCOBTF100RLQ, TCAN1042DRBQ1, TCAN1042HVDRBQ1, TCAN1051VDRBQ1, TPS717XXQDRVQ1, LP5912Q1.2DRVVRQ1, LP3971SQ-D510/NOPB, TPS62261DRV, and TPS61025DRC are qualified at L1-260C MSL rating. TPS22990DML, TPD5S330RJK, ONET4291VARGP, CDCM1804RGE, TPS65992DADRJK, DS125BR401Q4DK, TPS62170DSG, LM73606QRNPQ1, TIOL1XXDMW, TPS61025DRC, and TPS62080ADSG are qualified at L2-260C MSL rating. ADS8548SRGC, SH6966ACC0RGC, SH6966ADU0RGC, MSP430FR5739IRHA, UCD9211RHA, TPS65126RSH, TPS65988CFRSH, CC2541F256RHA, TLC6983RRF, and DP83848LFQSQE are qualified at L3-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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